

ADE-208-030B(Z)

HSM2836C

Silicon Epitaxial Planar Diode for High Speed Switching

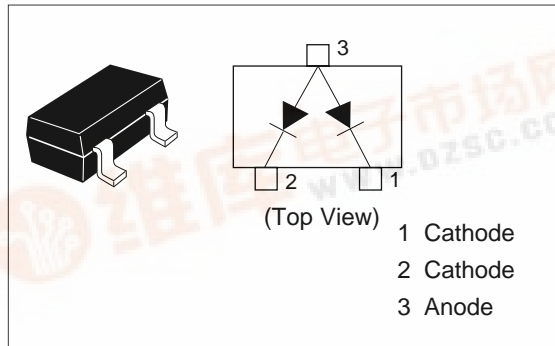
HITACHI

Rev. 2
Aug. 1995

Features

- Fast recovery time.
- MPAK package is suitable for high density surface mounting and high speed assembly.

Pin Arrangement



Ordering Information

Type No.	Laser Mark	Package Code
HSM2836C	A 4	MPAK

Absolute Maximum Ratings ** (Ta = 25°C)

Item	Symbol	Value	Unit
Peak reverse voltage	V_{RM}	85	V
Reverse voltage	V_R	80	V
Peak forward current	I_{FM}	300	mA
Non-Repetitive peak forward surge current	I_{FSM}^*	4	A
Average forward current	I_o	100	mA
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

* Within 1 μ s forward surge current.

** Per one device

Electrical Characteristics * (Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_{F1}	—	0.72	1.0		$I_F = 10 \text{ mA}$
	V_{F2}	—	0.83	1.0	V	$I_F = 50 \text{ mA}$
	V_{F3}	—	0.90	1.2		$I_F = 100 \text{ mA}$
Reverse current	I_R	—	—	0.1	μA	$V_R = 80 \text{ V}$
Capacitance	C	—	2.5	4.0	pF	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$
Reverse recovery time	t_{rr}	—	—	20	ns	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}, R_L = 50 \Omega$

* Per one device

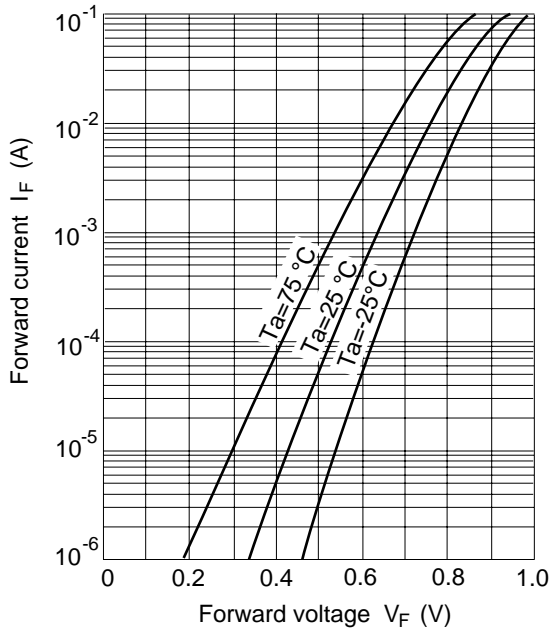


Fig.1 Forward current Vs. Forward voltage

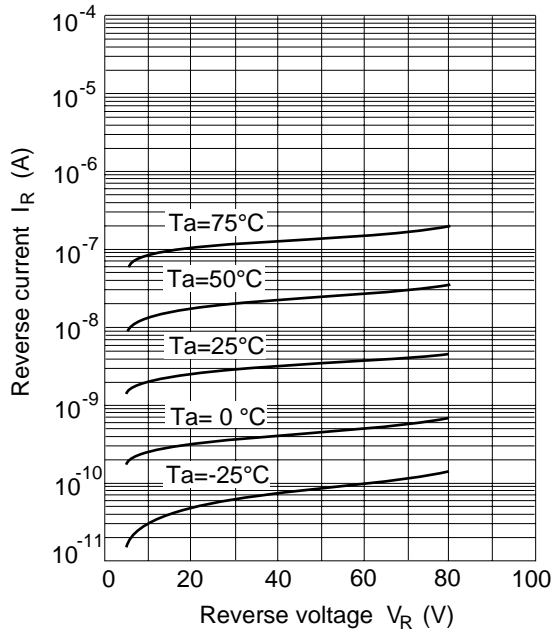


Fig.2 Reverse current Vs. Reverse voltage

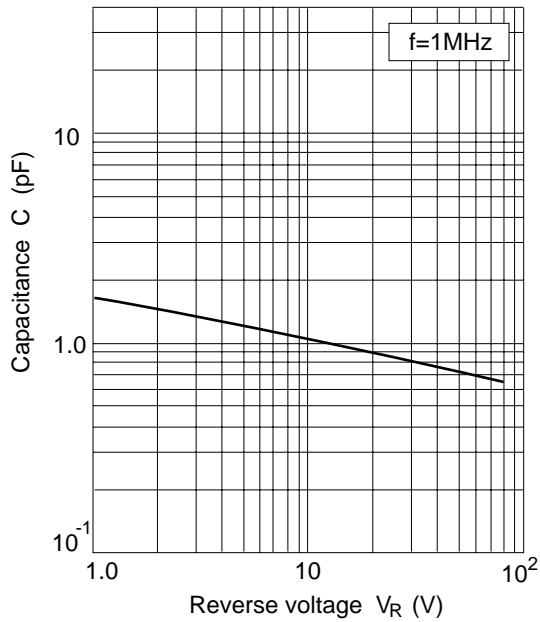


Fig.3 Capacitance Vs. Reverse voltage

Package Dimensions

Unit: mm

